

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	KEIO UNIVERSITY	06/24/2022
RECEIVING PARTY DATA		
Name:	TSUBOTA LABORATORY, INC.	
Street Address:	TOSHIN SHINANOMACHI -EKIMAE BLDG. 304, 34, SHINANOMACHI	
City:	SHINJUKU-KU, TOKYO 1600016	
State/Country:	JAPAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14901518
CORRESPONDENCE DATA		
Fax Number:	(312)419-9440	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	312-380-6504	
Email:	dgurfinkel@dennemeyer-law.com	
Correspondent Name:	DANIEL M. GURFINKEL	
Address Line 1:	DENNEMEYER & ASSOCIATES, LLC	
Address Line 2:	2 NORTH RIVERSIDE PLAZA, SUITE 1500	
Address Line 4:	CHICAGO, ILLINOIS 60606	
ATTORNEY DOCKET NUMBER:	30100-10165753P 1439880	
NAME OF SUBMITTER:	DANIEL M. GURFINKEL	
SIGNATURE:	/daniel m. gurfinkel/	
DATE SIGNED:	09/10/2022	
Total Attachments: 1		
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UNITED STATES OF AMERICA

ASSIGNMENT OF PATENT

U.S. Patent No.: **14/901518**

For good and valuable consideration in hand paid, the receipt and sufficiency whereof are hereby acknowledged, **KEIO UNIVERSITY**, an university organized under the laws of Japan, having an address at 15-45, Mita 2-Chome, Minato-Ku Tokyo, 108-8345 Japan (Assignor), hereby sells, assigns, transfers and sets over to **TSUBOTA LABORATORY, INC.**, a corporation organized under the laws of Japan, having an address at Toshin Shinanomachi-ekimae Bldg. 304, 34, Shinanomachi, Shinjuku-ku, Tokyo 1600016 Japan (Assignee) and to the successors and assigns of Assignee, the entire right, title and interest in the invention or improvements of the undersigned disclosed in the U.S. Patent Nos. mentioned above; THEREOF, and in said patents and any and all other applications, both United States and foreign, which the undersigned may have filed and/or may file, either solely or jointly with others, on said inventions or improvements in any United States or foreign patent application claiming priority from, or claiming the same or improved invention as, any or all of the applications upon which said U.S. Patents issued, and in any and all Letters Patent or industrial models of the United States and foreign countries which may be obtained on any of said applications and in any reissue or extension of such patents, for the full term or terms for which said Patent, Patents or Industrial Design are or may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by Assignor had this assignment and sale not been made; together with all claims for damages by reason of past infringement of any or all of said Patents with the right to sue for and collect the same.

Assignor warrants itself to be the owner of the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrants that there are no outstanding prior assignments, licenses, or other encumbrances on the interests herein assigned. Assignor hereby covenants that no other assignment, sale, agreement or encumbrance will be made or entered into which would conflict with this sale and assignment.

Assignor further covenants that Assignee will, upon its request and at the expense of Assignee, be provided promptly with all pertinent facts and documents relating to said inventions and said Letters Patents and legal equivalents as may be known and accessible to Assignor and will testify or cause appropriate persons to testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute or have executed, to the best of its ability, and deliver to Assignee or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce any and all of said applications, said inventions and said letters patent and foreign equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

KEIO UNIVERSITY

Jun 24, 2022
Date


By: **KOHEI ITOH**
(Name and Title) President

To be simply signed